

GP1A073LCS

Gap: 5mm Slit: 0.5mm
*OPIC Output,
Snap-in type
Transmissive Photointerrupter with
Connector

■ Description

GP1A73AJ000F is a standard, OPIC output, transmissive photointerrupter with opposing emitter and detector in a case, providing non-contact sensing. For this family of devices, the emitter and detector are inserted in a case, and a 3-pin connector is included to allow remotemount or off-board designs.

■ Features

- 1. Transmissive with OPIC output
- 2. Highlights:
 - Special position hooks compatible with 3 different wall thicknesses (1.0, 1.2, 1.6mm)
 - Hinged snap insertion
 - Wide operation voltage (2.7 to 5.5V)
- 3. Key Parameters:
 - · Gap Width: 5mm
 - · Slit Width (detector side): 0.5mm
 - Package: 17×12.8×8mm (without connector and hooks)
 - Connector: Tyco Electronics AMP K.K. (PN: 292133-3)

or SUMIKO TEC CO., LTD. (PN: GH4A003P000ZA)

- Output Type: High when the object is present with Pullup Resistor.
- 4. Lead free and RoHS directive compliant

■ Agency approvals/Compliance

1. Compliant with RoHS directive

■Applications

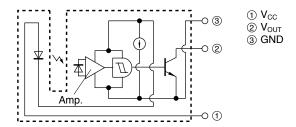
- General purpose detection of object presence or motion.
- 2. Example: PPC, FAX, Printer

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^{* &}quot;OPIC"(Optical IC) is a trademark of the SHARP Corporation. An OPIC consists of a light-detecting element and a signal-processing



Internal Connection Diagram

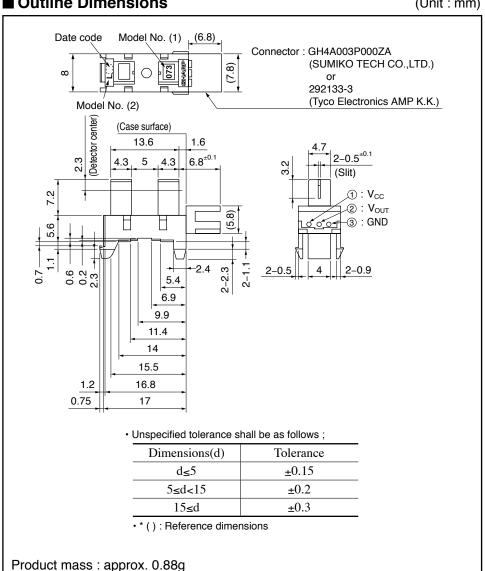


Truth table (In case of external addition pull-up resistance to Vout terminal)

Condition	Output
Light beam interrupted	High
Light beam uninterrupted	Low

■ Outline Dimensions

(Unit: mm)



Connector terminal plating material: Sn (PN: 292133-3) or SnCu (PN: GH4A003P000ZA)



Date code (2 digit)				
1st o	digit	2nd	digit	
Year of p	roduction	Month of production		
A.D.	Mark	Month	Mark	
2000	0	1	1	
2001	1	2	2	
2002	2	3	3	
2003	3	4	4	
2004	4	5	5	
2005	5	6	6	
2006	6	7	7	
2007	7	8	8	
2008	8	9	9	
2009	9	10	X	
2010	0	11	Y	
:	:	12	Z	

repeats in a 10 year cycle

Country of origin

Japan or Philippines (Indicated on the packing case)



■ Absolute Maximum Ratings $(T_a=25^{\circ}C)$				
Parameter	Symbol	Rating	Unit	
Supply voltage	V_{CC}	-0.5 to +7	V	
*1 Output voltage	V _{OUT}	-0.5 to +7	V	
*2 Output current	I _{OL}	8	mA	
*3 Operating temperature	Topr	-20 to +75	°C	
*3 Storage temperature	T _{stg}	-30 to +85	°C	

■ Electro-optical Characteristics

 $(V_{CC}=5V, T_a=25^{\circ}C)$

	•						-a/
	Parameter Symbol Conditions		MIN.	TYP.	MAX.	Unit	
Low level sup	oply current	I_{CCL}	I _{CCL} Light beam uninterrupted		_	16.5	mA
Low level out	tput voltage	V_{OL}	V _{OL} Light beam uninterrupted, I _{OL} =4mA		_	0.35	V
High level supply current I _{CCH} Light beam interrupted		_	_	16.5	mA		
High level output voltage		V _{OH}	Light beam interrupted, $R_L=47k\Omega$	V _{CC} ×0.9	_	_	V
Operating sup	pply voltage	V_{CC}	-	2.7	_	5.5	V
Response	Min. interrupted time	t _H	P. 4.7kO	166	_	_	
characteristics	Min. uninterrupted time	$t_{\rm L}$	$R_L=4.7k\Omega$		_	_	μs

^{*1} Collector-emitter voltage of output transistor.
*2 Collector current of output transistor, refer to Fig.1.
*3 The connector should be plugged in/out at normal temperature.



Fig.1 Output Current vs.

Ambient Temperature

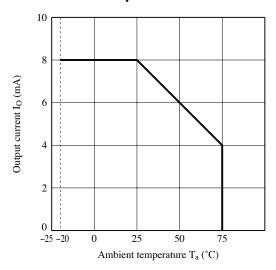
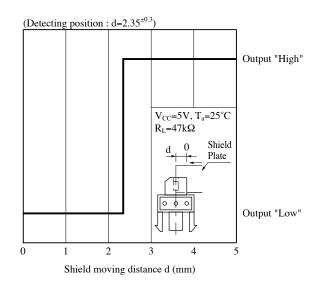
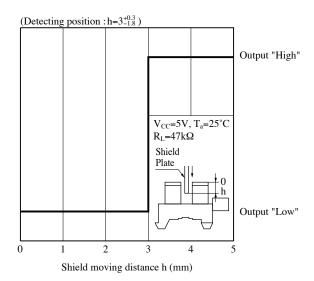


Fig.2 Detecting Position Characteristics (1)

Fig.3 Detecting Position Characteristics (2)





Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.



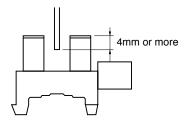
■ Design Considerations

Design guide

- 1) Prevention of detection error
 - To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.
- 2) In order to stabilize power supply line, connect a by-pass capacitor of more than $0.01\mu F$ between V_{CC} and GND near the device.
- 3) When the sensor is connected with long wire, noise might be on the signal from the sensor while it is going through the wire. To avoid this problem, please evaluate the sensor under actual usage condition to make sure that the system works fine.
- 4) Position of opaque board

Opaque board shall be installed at place 4mm or more from the top of elements.

(Example)



This product is not designed against irradiation and incorporates non-coherent IRED.

Parts

This product is assembled using the below parts.

Photodetector (qty.: 1) [Using a silicon photodiode as light detecting portion, and a bipolar IC as signal processing circuit]

Category	Material	Maximum Sensitivity wavelength (nm)	Sensitivity wavelength (nm)	Response time (μs)
Photodiode	Silicon (Si)	900	400 to 1 200	10

Photo emitter (qty.: 1)

Category	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared emitting diode (non-coherent)	Gallium arsenide (GaAs)	950	0.3

Material

Case	Lead frame	Connector terminal finish
Black polycarbonate resin	42Alloys	Sn plating (PN : 292133-3)
(UL94 V-2)	(There is no plating)	SnCu plating (PN : GH4A003P000ZA)

Others

Laser generator is not used.

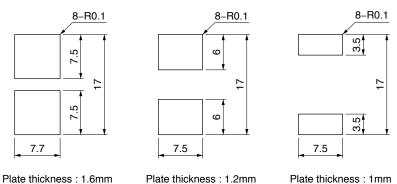
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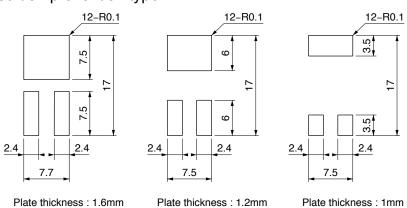
Recommended Installation Hole drawing

- 1) We recommend to fix the product at punching side on the fixing plate (metal plate).
- 2) Please decide the final dimensions at your side after confirmation by the actual applications, Because mounting efficiency and mounted stabilization are dependent on mounting hole corner curve and punched state.
- 3) Tolerance shall be ±0.1mm

Normal type



Reverse-insertion prevention type





■ Manufacturing Guidelines

Notes of cleaning

Please carry out neither the immersion cleaning nor the ultrasonic cleaning to avoid the solvent residue inside the case.

When necessary, dust and stain shall clean by air-blow or wipe off by soft cloth soaked in cleaning agent. The cleaning agent used to wipe off must use only the following kind. Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances: CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

•Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

Sheet No.: D3-A04701EN



■ Package specification

Case package

Package materials

Anti-static plastic bag: Polyethtylene

Moltopren: Urethane

Partition: Corrugated fiberboard
Packing case: Corrugated fiberboard

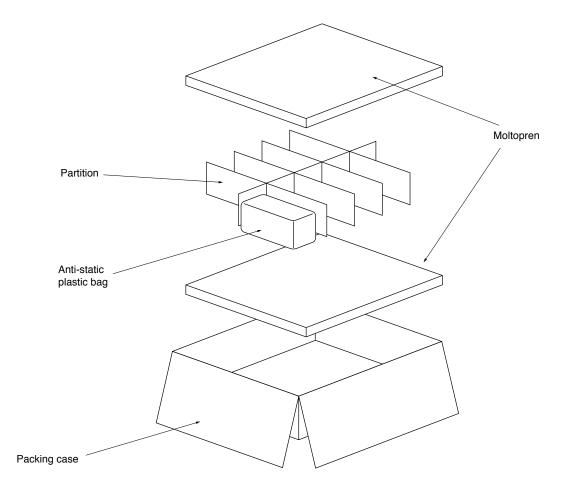
Package method

100 pcs of products shall be packaged in a plastic bag, Ends shall be sealed by stapler. The bottom of the packing case is covered with moltopren, and the partition is set in the packing case. Each partition should have 1 plastic bag.

The 10 plastic bags containing a product are put in the packing case.

Moltopren should be located after all product are settled (1 packing conteains 1 000 pcs).

Packing composition





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